US00D443538S

(12) **United States Design Patent**
Wrisley et al.

(10) **Patent No.: US D443,538 S**
(45) **Date of Patent: ** Jun. 12, 2001**

(54) **PROCESSOR AND DISPLAY MODULE FOR A MODULAR MEASUREMENT INSTRUMENT**

(75) Inventors: **Jerry L. Wrisley**, Beaverton; **James H. McGrath, Jr.**, Aloha, both of OR (US)

(73) Assignee: **Tektronix, Inc.**, Beaverton, OR (US)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/120,012**

(22) Filed: **Mar. 13, 2000**

(51) **LOC (7) Cl.** **10-04**

(52) **U.S. Cl.** **D10/78**

(58) **Field of Search** D10/46, 75, 78, D10/81; D14/100; 73/336.5, 431; 128/630, 745, 746; 340/573.1, 578.3, 601, 576, 521; 600/301, 300, 368; 364/413.07, 413.02, 413.08, 413.09; 324/158

(56) **References Cited**

U.S. PATENT DOCUMENTS

D. 383,400	*	9/1997	Wada	D10/65
D. 412,156	*	7/1999	Mizusugi et al.	D14/100
5,410,474	*	4/1995	Fox	600/300
6,111,501	*	8/2000	Honeyager et al.	340/521

* cited by examiner

Primary Examiner—Antoine Duval Davis
(74) *Attorney, Agent, or Firm*—William K. Bucher; Francis I. Gray

(57) **CLAIM**

The ornamental design for a processor and display module for a modular measurement instrument, as shown and described.

DESCRIPTION

The ornamental design disclosed in this application is for a processor and display module for a modular for a modular measurement instrument having raised bumper guards at the corners of the module, and a bi-level rear surface.

FIG. **1** is a perspective view of a processor and display module for a modular measurement instrument;

FIG. **2** is a front elevation view of the processor and display module for a modular measurement instrument;

FIG. **3** is a rear elevation view of the processor and display module for a modular measurement instrument;

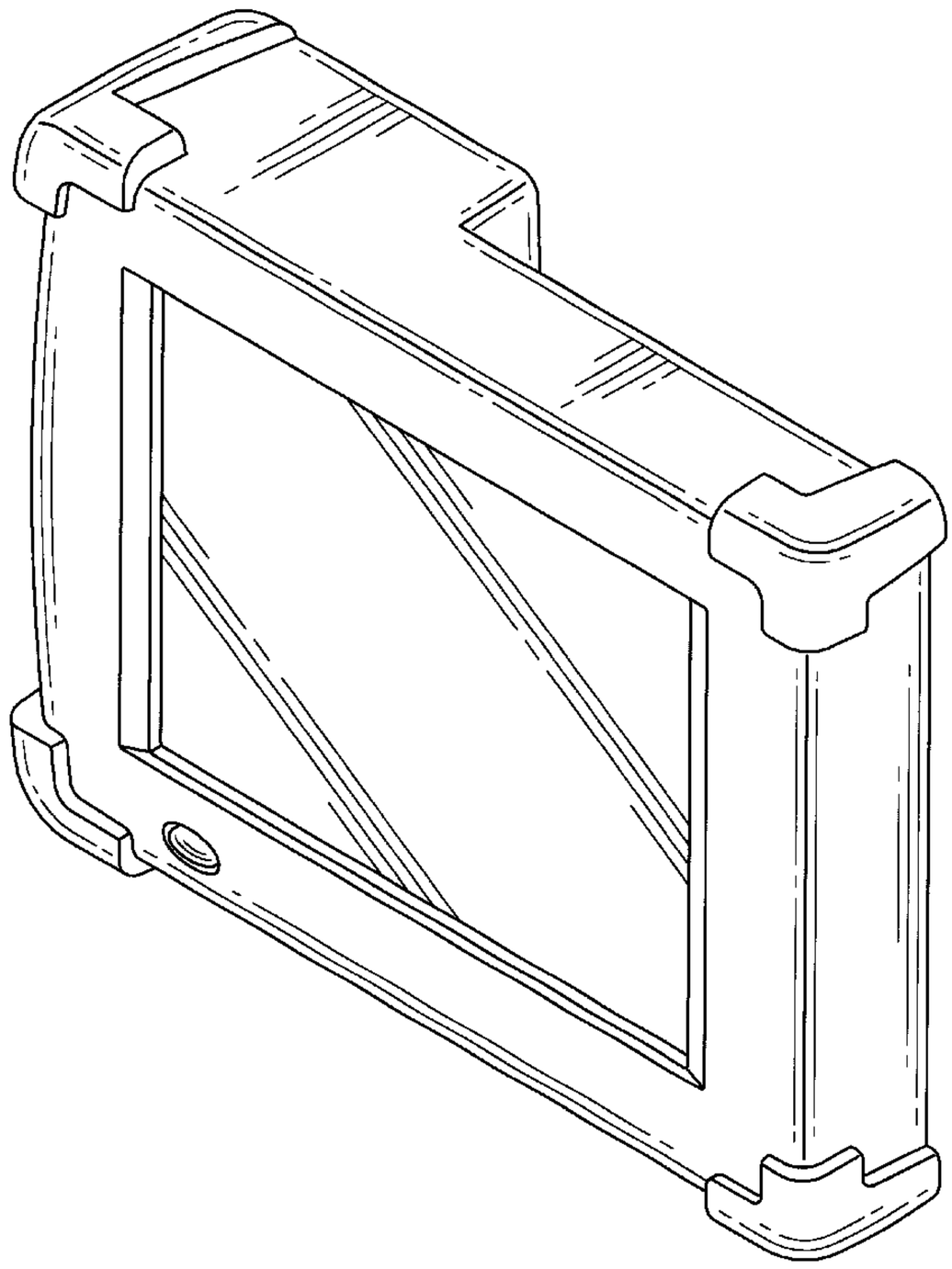
FIG. **4** is a left side elevation view of the processor and display module for a modular measurement instrument;

FIG. **5** is a right side elevation view of the processor and display module for a modular measurement instrument.

FIG. **6** is a top plan view of the processor and display module for a modular measurement instrument; and,

FIG. **7** is a bottom plan view of the processor and display module for a modular measurement instrument.

1 Claim, 5 Drawing Sheets



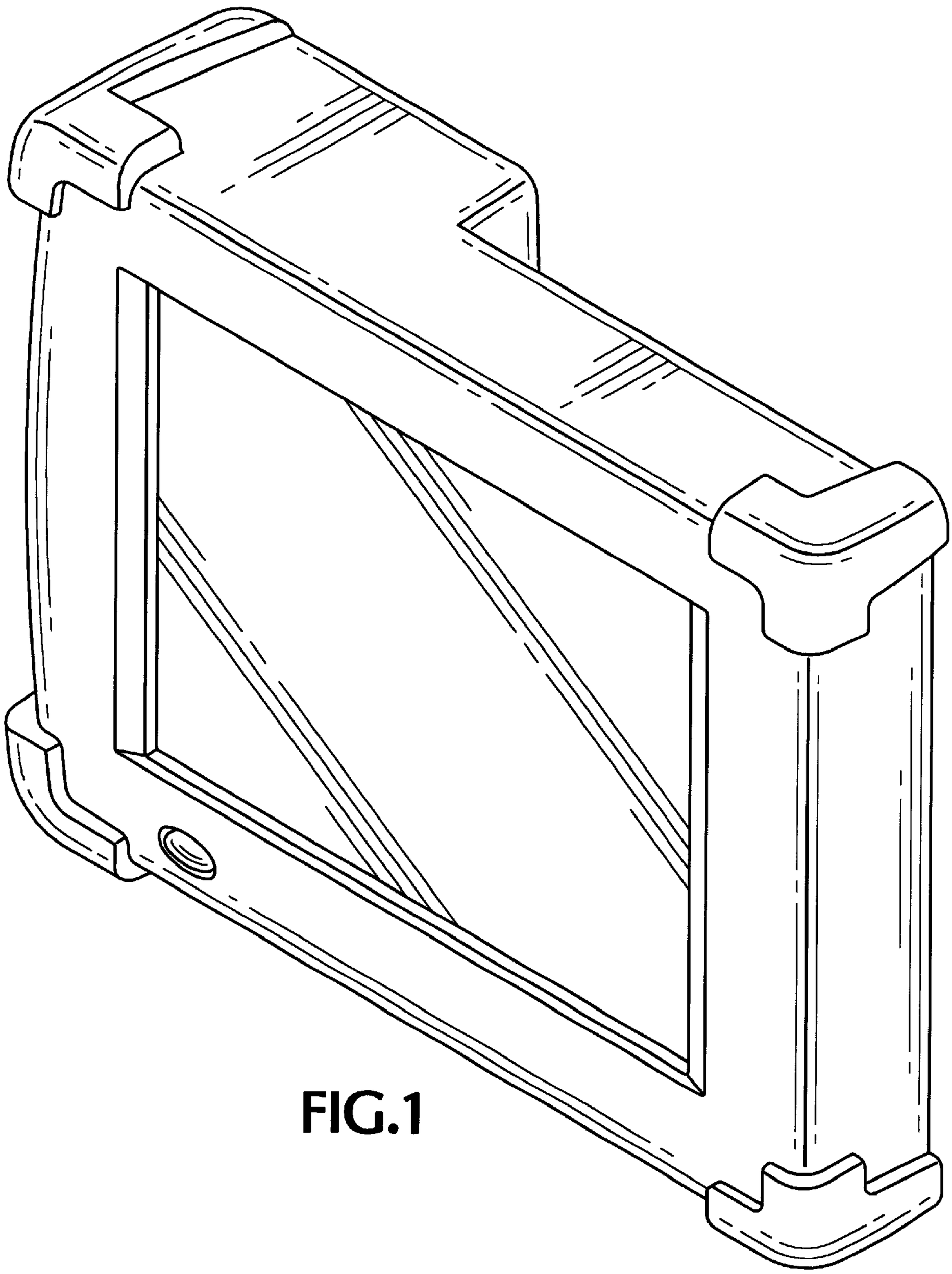


FIG.1

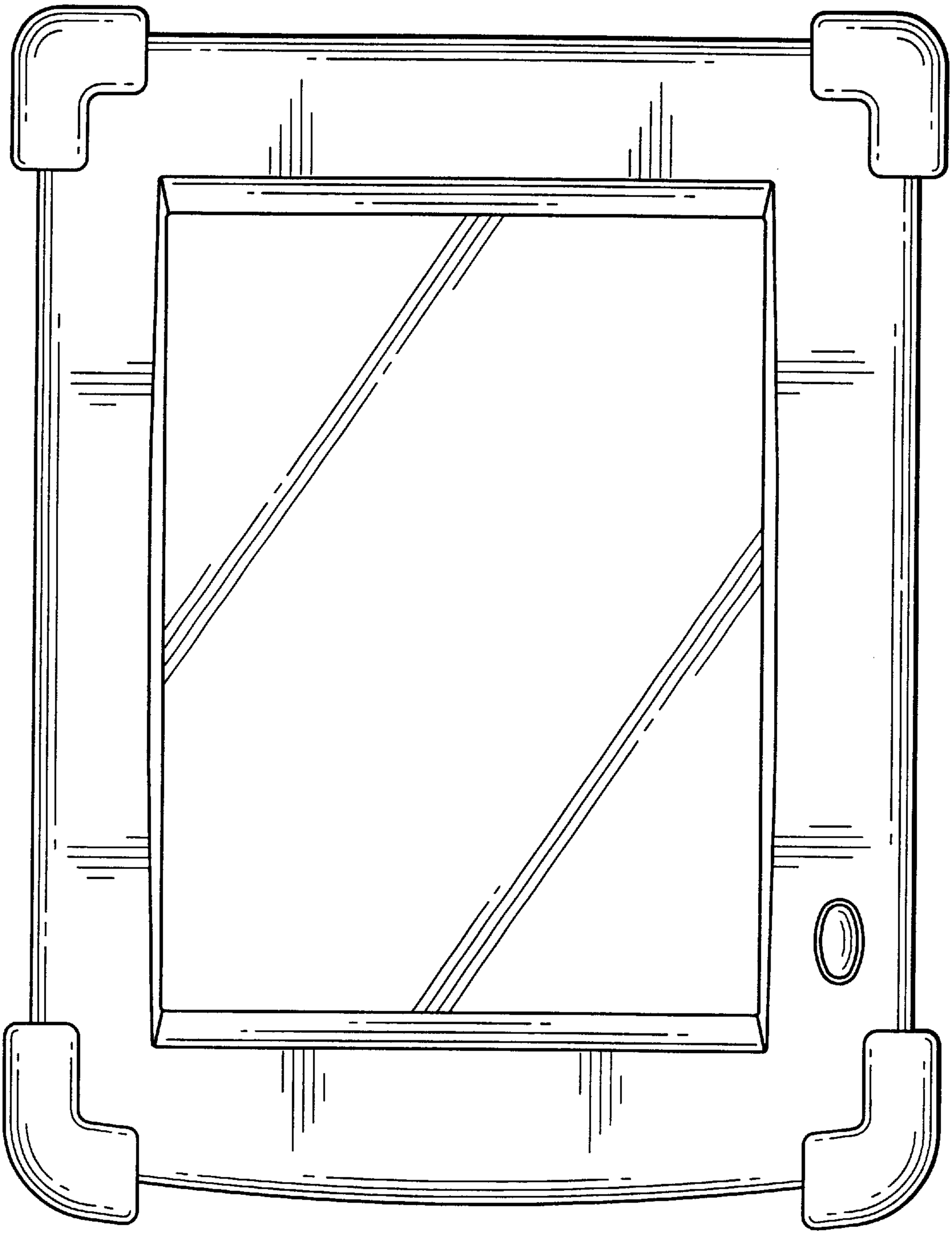


FIG.2

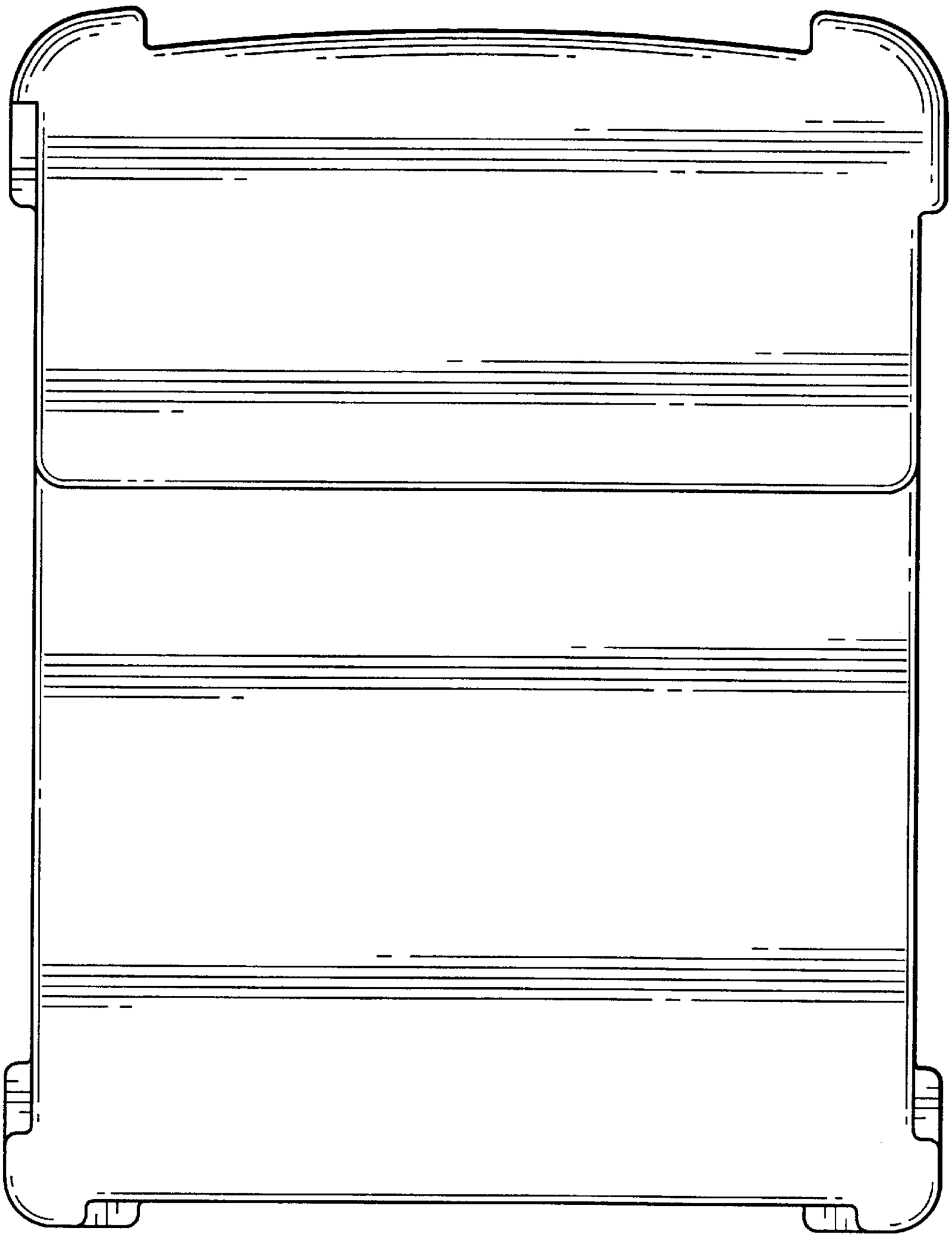


FIG. 3

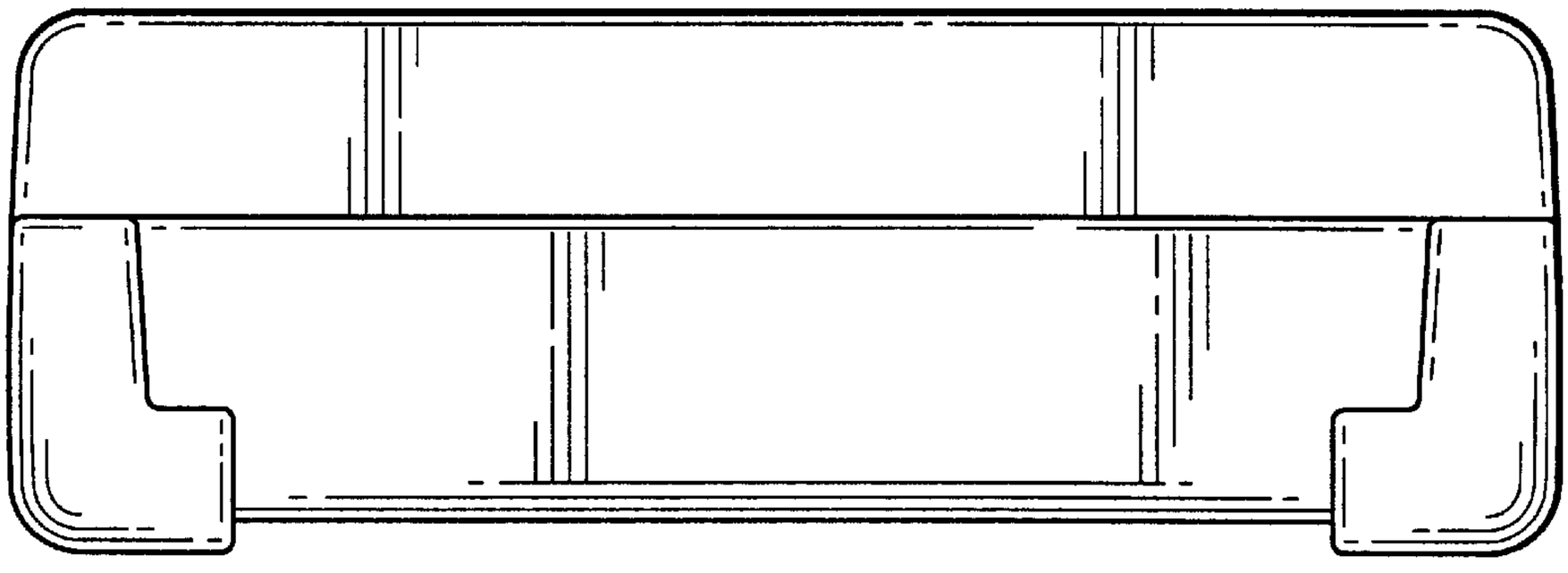


FIG.5

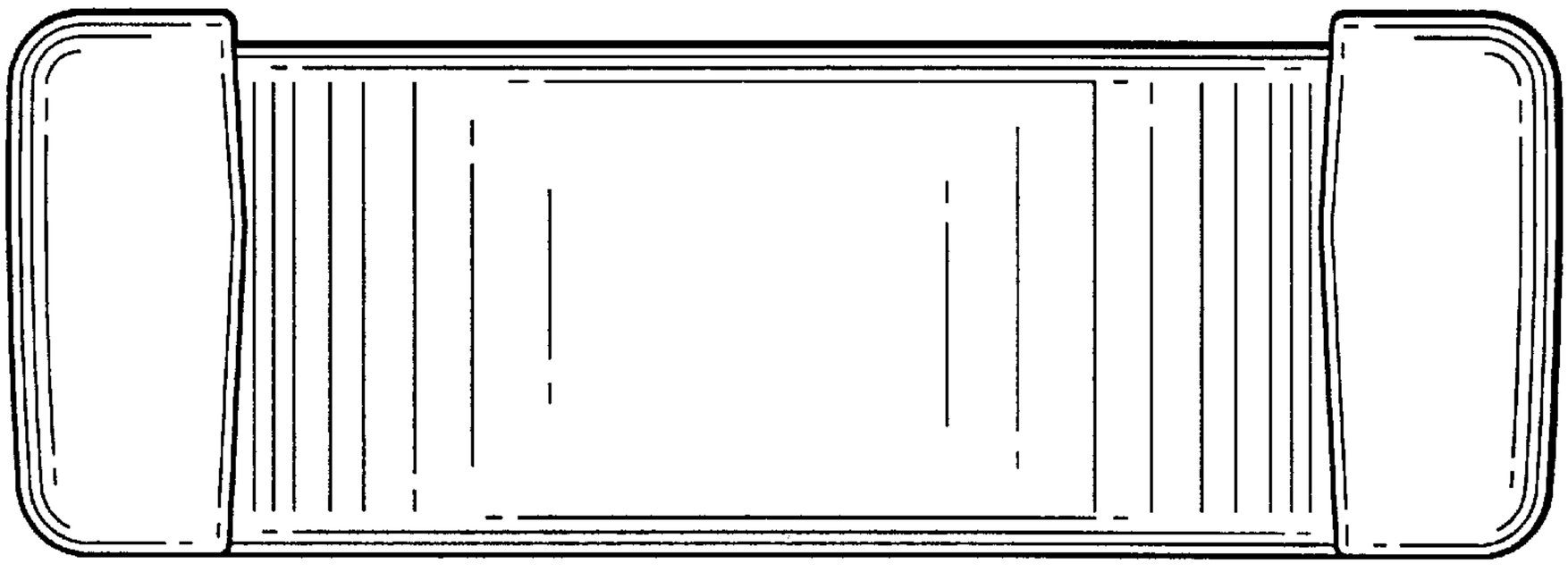


FIG.4

FIG.6

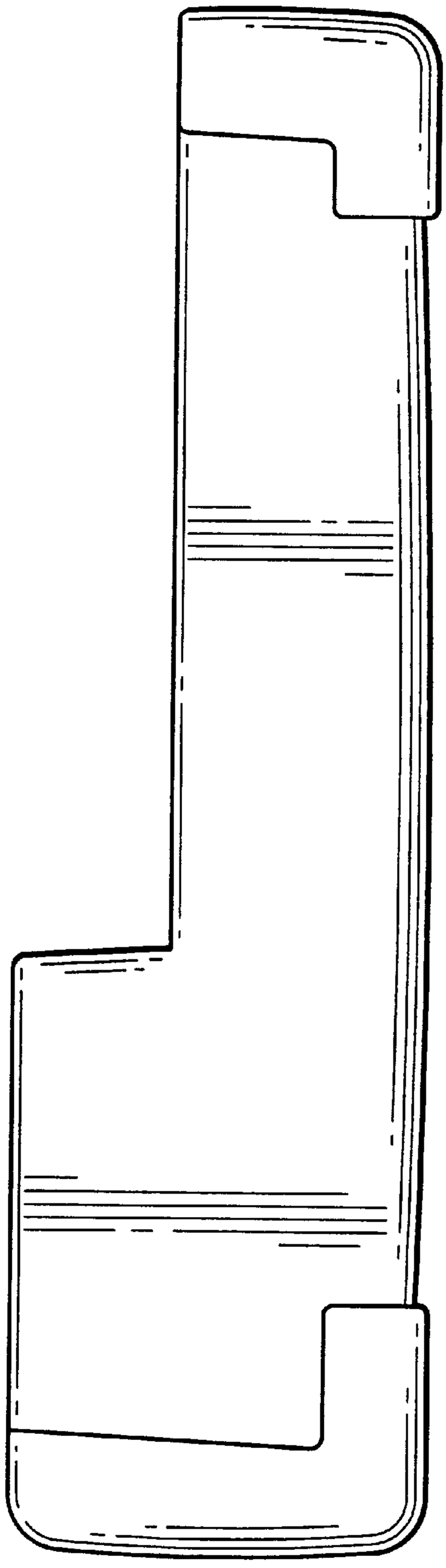


FIG.7